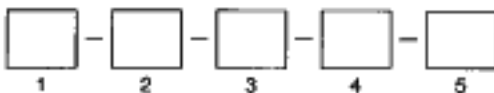


PLASTIC LEADED CHIP CARRIER

*High Density Configuration Available

**ORDERING INFORMATION****1. DESCRIPTION**

PLCC = Plastic Leaded Chip Carrier

2. POSITION

20, 28, 32, 44, 52, 68, 84, 100

3. MOUNTING ANGLE

TB = Through Board

SM = Surface Mount

4. PLATING

G = Gold over Nickel

T = Tin

5. SPECIAL OPTIONSN = Thin wall for high density
(available in 32, 44, 68, 84)**FEATURES:**

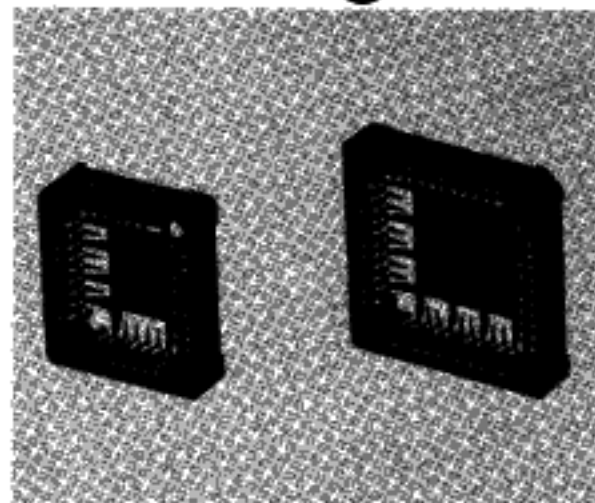
- Converts .050" chip centers to .100" board hole spacing
- Visual polarization for proper assembly orientation
- Closed bottom eliminates bridging and solder wicking
- Superior contact design allows proper seating and retention of JEDEC A, B and D chips

PLCC SERIES SPECIFICATIONS:**MATERIALS:**

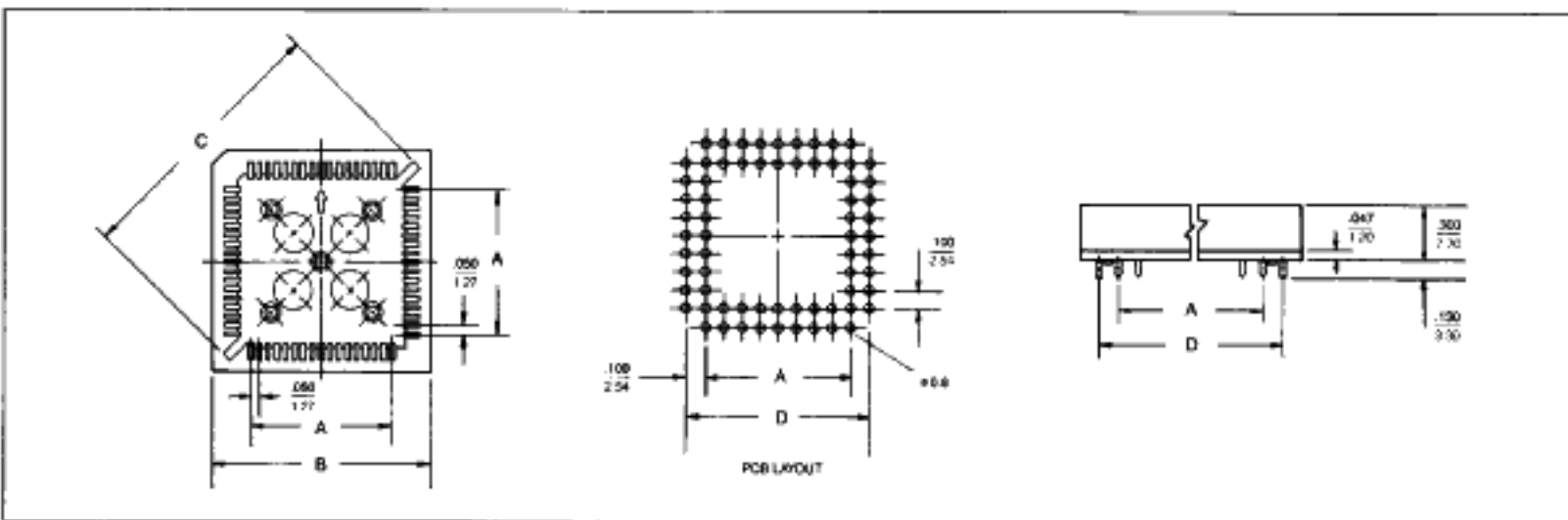
Contacts Phosphor Bronze
 Plating Tin or gold over nickel
 Insulator PPS high temp.
 UL 94V-0

ELECTRICAL:

Current Rating 1 Amp DC
 Dielectric withstanding voltage: 1000 VAC
 Insulation Resistance 1000 megohms min.
 Contact Resistance 5 milliohms typ. 20 max.
 Operating Temperature -65 to + 110 C

**DIMENSIONAL DATA**

All dimensions in (inches) and millimeters.



No. of Contact Pos.	A	B	C	D
20	5.08 (.200)	15.58 (.613)	18.30 (.720)	16.16 (.400)
28	7.62 (.300)	18.12 (.713)	21.86 (.860)	12.70 (.500)
32	7.62 (.300)	17.60 (.692)	23.00 (.905)	12.60 (.496)
44	12.70 (.500)	24.50 (.960)	30.04 (1.180)	17.78 (.700)
52	15.24 (.600)	27.00 (1.060)	32.64 (1.290)	20.32 (.800)
68	20.32 (.800)	32.00 (1.260)	38.70 (1.560)	25.40 (1.000)
84	25.40 (1.000)	37.10 (1.460)	46.90 (1.850)	30.48 (1.200)
100	31.75 (1.250)	42.26 (1.664)	54.10 (2.130)	35.56 (1.400)